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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKETING	
10/665,697	09/22/2003		ATTORNEY DOCKET NO.	CONFIRMATION NO.
	07/22/2003	James M. Cleeves	3558P022D2	6036
	7590 06/02/2004		EXAMINER	
BLAKELY SOKOLOFF TAYLOR & ZAFMAN 12400 WILSHIRE BOULEVARD, SEVENTH FLOOR			NGUYEN, TUAN H	
LOS ANGELES, CA 90025			ART UNIT	PAPER NUMBER
			2813	
			DATE MAILED: 06/02/2004	

Please find below and/or attached an Office communication concerning this application or proceeding.

The MAILING DATE of this communication appeared Period for Reply A SHORTENED STATUTORY PERIOD FOR REPLY I THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.136(after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days a new less than thirty (30) days and the new less than thirty (30) days a new less than thirty (30) days and the new less than the new less th		CLEEVES, JA Art Unit 2813 th the correspondence	
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 If the period for reply specified above is less than thirty (30) days, a reply will not period for reply is specified above, the maximum statutory period will. Failure to reply within the set or extended period for reply will, by statute, can have reply received by the Office later than three months after the mailing day earned patent term adjustment. See 37 CFR 1.704(b). 	a). In no event, however, may a reathin the statutory minimum of thirty apply and will expire SIX (6) MONT	ply be timely filed (30) days will be considered HS from the mailing date of t	timely.
Status			•
1) Responsive to communication(s) filed on 22 Sept	tombor 2002		
	ction is non-final.	•	, et a e a e e e e e e e e e e e e e e e e e e
/E3 //// W	Such to formal make		
3) Since this application is in condition for allowance closed in accordance with the practice under Exp	narte Ougulo 1035 C.D.	rs, prosecution as to	the merits is
	Jante Quayle, 1935 C.D.	11, 453 O.G. 213.	
Disposition of Claims			
4) Claim(s) 31-40 is/are pending in the application.			
4a) Of the above claim(s) is/are withdrawn	from consideration.		
5) Claim(s) is/are allowed.	• •		
6)⊠ Claim(s) <u>31-40</u> is/are rejected.			
7) Claim(s) is/are objected to.			
8) Claim(s) are subject to restriction and/or el	ection requirement.		*
Application Papers			· · · · · · · · · · · · · · · · · · ·
9) The specification is objected to by the Examiner.			
10) ☐ The drawing(s) filed on is/are: a) ☐ accepte	ed or b) Objected to by	the Examiner.	
Applicant may not request that any objection to the drav	ving(s) be held in abeyance	e. See 37 CFR 1.85(a)	
Replacement drawing sheet(s) including the correction in	is required if the drawing(s)	is objected to Sec 37	CED 4 404/4)
11) The oath or declaration is objected to by the Exam	iner. Note the attached (Office Action or form	PTO-152.
Priority under 35 U.S.C. § 119			
12) Acknowledgment is made of a claim for foreign price a) All b) Some * c) None of: 1. Certified copies of the priority documents hat 2. Certified copies of the priority documents hat 3. Copies of the certified copies of the priority of application from the International Bureau (Potensian See the attached detailed Office action for a list of the	ve been received. ve been received in App locuments have been re CT Rule 17.2(a)).	lication No ceived in this Nation	al Stage
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Attachment(s)	•		
1) Notice of References Cited (PTO-892)	4) Interview Sum	mary (PTO-413)	
2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)	Paper No(s)/M	ail Date	
Paper No(s)/Mail Date	5) Notice of Information (6) Other:	mal Patent Application (P	ΓΟ-152)
S. Patent and Trademark Office	··		·

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DETAILED ACTION

The disclosure is objected to because of the following informalities: On page 1, next to last line, serial number "09/841,727" should be correctly changed to – 09/814,727--.

Appropriate correction is required.

Claim Rejections - 35 USC § 112

The following is a quotation of the second paragraph of 35 U.S.C. 112:

The specification shall conclude with one or more claims particularly pointing out and distinctly claiming the subject matter which the applicant regards as his invention.

Claims 36, 39-40 are rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.

In claim 36, it is unclear as to how could the first, second and third rail-stacks have approximately the same height when the second rail-stack having more layers than that of the first and the third rail-stacks? (Specification, page 14, [0040]-[0041] that discloses that same height only applies for middle rail-stacks, not for lowest and highest rail-stack levels).

In claim 39, last five lines are confusing and indefinite, since it is unclear as to how could the third rail-stack is formed by etching the third conductive layer, and the etched fourth semiconductor layer which is covered by the antifuse layer, without etching the antifuse layer?

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Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(e) the invention was described in a patent granted on an application for patent by another filed in the United States before the invention thereof by the applicant for patent, or on an international application by another who has fulfilled the requirements of paragraphs (1), (2), and (4) of section 371(c) of this title before the invention thereof by the applicant for patent.

The changes made to 35 U.S.C. 102(e) by the American Inventors Protection Act of 1999 (AIPA) and the Intellectual Property and High Technology Technical Amendments Act of 2002 do not apply when the reference is a U.S. patent resulting directly or indirectly from an international application filed before November 29, 2000. Therefore, the prior art date of the reference is determined under 35 U.S.C. 102(e) prior to the amendment by the AIPA (pre-AIPA 35 U.S.C. 102(e)).

Claims 31-38 are rejected under 35 U.S.C. 102(e) as being anticipated by Knall et al.(cited by applicant).

Knall et al., figs. 1-7 and text on col. 2-10 discloses the claimed method for fabricating two memory levels in a memory array including forming a first conductive layer 14, depositing a doped first semiconductor layer 15 over the first conductive layer 14 (fig. 1, col. 3, paragraphs 2, 3, 4); etching the first conductive layer 14 and the first semiconductor layer 15 into a plurality of first parallel, spaced-apart (half) rail-stacks (col. 3, fourth paragraph); filling and planarizing the space between the first rail-stacks with a first insulator (col. 3, lines 45-47, col. 4, second paragraph); forming a first antifuse layer 20 over the planarized first upper surface (col. 3, lines 41-47); depositing

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a doped second semiconductor layer 21 over the first antifuse layer 20; forming a second conductive layer 23 over the doped second semiconductor layer 21; depositing a doped third semiconductor layer 24 over the second conductive layer 23; etching the second semiconductor layer 21, second conductive layer 23, and third semiconductor layer 24 into a plurality of second parallel, spaced-apart (full) rail stacks (col. 3, last paragraph); filling and planarizing the space between the second rail-stacks with a second insulator (col. 4, second paragraph); forming a second antifuse layer 26 on the planarized second upper surface (col. 4, third paragraph); depositing a doped fourth semiconductor layer 28, 30 over the second antifuse 26, forming a third conductive layer 31; etching the doped fourth semiconductor layer 28, 30, third conductive layer 31 to form third parallel, spaced-apart rail-stacks (fig. 1); filling the space between the third rail-stacks with a third insulator (coll. 4, second paragraph).

With respect to claim 32, see col. 3, lines 29-33 which discloses the semiconductor material (first, second third and fourth semiconductor layers) such as silicon layer is typically polysilicon.

With respect to claim 33, 34, fig. 3 shown the concentration of N-,P+ of polysilicon layers 47, 52 having opposite conductivity type for forming diode.

With respect to claim 35, see col. 3, lines 40-45, col. 4, third paragraph for the antifuse material formed from a dielectric such as silicon dioxide.

With respect to claim 36, insofar, as understood, is shown in fig. 3 wherein the full (middle) rail-stacks 3, 4, 5,6 having the same number of layers therefore having approximately the same height.

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With respect to claim 37, see col. 3, third paragraph for the conductive layers' material including silicide.

The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. Cleeves et al., and Vyvoda et al. disclose related methods for forming antifuse structure.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Tuan H. Nguyen whose telephone number is 571-272-1694. The examiner can normally be reached on 9AM-5:30PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Carl Whitehead Jr. can be reached on 571-272-1702. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Tuan H. Nguyen Primary Examiner Art Unit 2813